

**COMBINED DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name, and I verily believe that I am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural inventors are named below, of the subject matter which is claimed and for which a patent is sought on the invention entitled: **METHOD AND DEVICE FOR REMOVING PARTICLES ON SEMICONDUCTOR WAFERS**, which:

(a) X is attached hereto. I hereby authorize any practitioner at Customer No. 23494, of Texas Instruments Incorporated, to insert in paragraph (b) below, the filing date and application number of said application when known.

(b) \_\_\_\_\_ was filed on \_\_\_\_\_ as Serial No. \_\_\_\_\_.

(c) \_\_\_\_\_ was described and claimed in PCT International Application No. \_\_\_\_\_ filed on \_\_\_\_\_ and as amended under PCT Article 19 on \_\_\_\_\_ (if any).

I have reviewed and understand the contents of the above identified specification, including the claims as amended by any amendment specifically referred to in the oath or declaration;

No application for patent or inventor's certificate on this invention has been filed by me or by my legal representatives or assigns in any country foreign to the United States of America, except as follows:

**Japanese Application No. 13(2001)-59777, filed March 5, 2001.**

I hereby claim benefit under Title 35, United States Code Section 119(a) of any foreign applications listed above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations Section 1.56(a);

I hereby claim benefit under Title 35, United States Code Section 119(e)(1) of any United States applications listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Serial No. \_\_\_\_\_ filed \_\_\_\_\_.

As a named inventor, I hereby appoint the following attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

**Practitioners at Customer Number: 23494**

Send correspondence and direct telephone calls to:

Jacqueline J. Garner  
Texas Instruments Incorporated  
PO Box 655474, M/S 3999  
Dallas, Texas 75265  
(972) 271-1176

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both under Section 1001 of Title 18 of the United States Code, and that such willful statements may jeopardize the validity of the application or any patent issuing thereon.

Name of Inventor: Toshihito Tsuga  
Residence and Post Office Address: 2-6 Nagakunidai  
Tsuchiura-shi Ibaraki  
Tsuchiura, 08  
Japan 300-0810  
Country of Citizenship: Japan

Inventor's signature: \_\_\_\_\_ Date: \_\_\_\_\_

Name of Inventor: Minoru Fube  
Residence and Post Office Address: 961-21 Ooaza Noharu  
Yamaga-machi  
Hayami-gun, Ooita  
Japan 879-1307

Country of Citizenship: Japan

Inventor's signature: \_\_\_\_\_ Date: \_\_\_\_\_

Name of Inventor: Kazutaka Nakayama  
Residence and Post Office Address: 3876-39 Kawasaki  
Hiji-machi  
Hayami-gun, Ooita  
Japan 879-1505

Country of Citizenship: Japan

Inventor's signature: \_\_\_\_\_ Date: \_\_\_\_\_